Silicon N-Channel MOS FET

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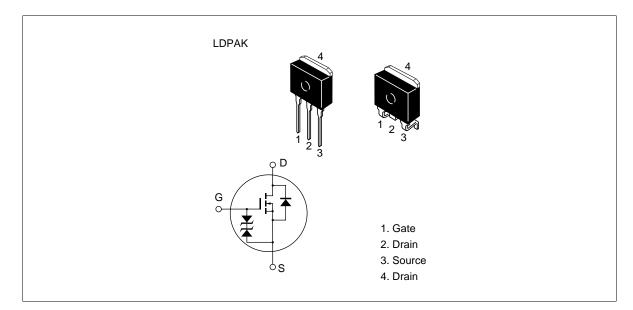
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- 4 V gate drive device
 - Can be driven from 5 V source
- Suitable for motor drive, DC-DC converter, power switch and solenoid drive

Outline





Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{(BR)DSS}$	100	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D	20	А
Drain peak current	I the second sec	80	А
Body to drain diode reverse drain current	l _{DR}	20	А
Channel dissipation	Pch*2	50	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Value at $T_c = 25^{\circ}C$

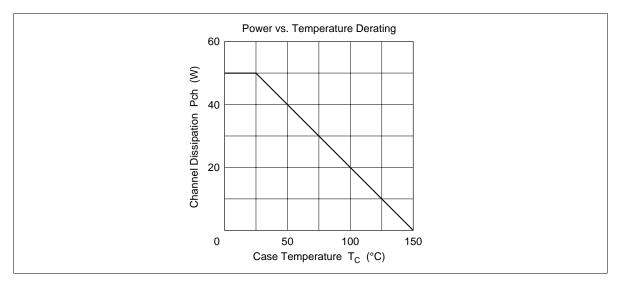
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Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	100	_	_	V	$I_{\rm D} = 10$ mA, $V_{\rm GS} = 0$
Gate to source breakdown voltage	$V_{(\text{BR})\text{GSS}}$	±20	—	—	V	$I_{g} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	—	_	250	μA	$V_{\rm DS} = 80 \ V, \ V_{\rm GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	_	2.0	V	$I_{\rm D} = 1 \text{ mA}, V_{\rm DS} = 10 \text{ V}$
Static Drain to source on state	$R_{DS(on)}$		0.065	0.085	Ω	$I_{\rm D} = 10$ A, $V_{\rm GS} = 10$ V *1
resistance		_	0.085	0.12	Ω	$I_{\rm D} = 10$ A, $V_{\rm GS} = 4$ V * ¹
Forward transfer admittance	yfs	10	16		S	$I_{\rm D} = 10$ A, $V_{\rm DS} = 10$ V *1
Input capacitance	Ciss	_	1300		pF	$V_{DS} = 10 \text{ V}, \text{ V}_{GS} = 0,$
Output capacitance	Coss	_	540		pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	160	_	pF	
Turn-on delay time	t _{d(on)}	_	12	_	ns	$I_{\rm D} = 10$ A, $V_{\rm GS} = 10$ V,
Rise time	t _r	—	100		ns	$R_L = 3 \Omega$
Turn-off delay time	$t_{d(off)}$	_	300	_	ns	
Fall time	t _f	_	150	_	ns	
Body to drain diode forward voltage	V_{DF}	_	1.3	_	V	$I_{\rm F} = 20$ A, $V_{\rm GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	—	300	—	ns	$I_F = 20 \text{ A}, V_{GS} = 0,$ $di_F/dt = 50 \text{ A}/\mu \text{s}$

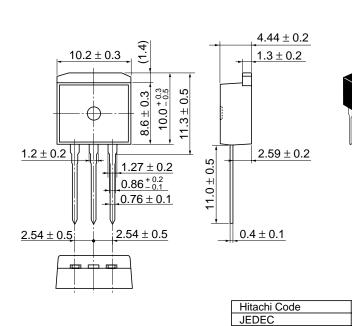
Electrical Characteristics (Ta = 25°C)

Note 1. Pulse test

See characteristic curves of 2SK1302.



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EIAJ

Unit: mm

LDPAK (L)

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EIAJ—Weight (reference value)1.4 g

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Semiconductor & Integrated Circuits. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109 URL NorthAmerica : http:semiconductor.hitachi.com/

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For further information write to: Hitachi Semiconductor Hitachi Europe GmbH

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose,CA 95134 Tel: <1> (408) 433-1990 Fax: <1>(408) 433-0223

Electronic components Group Domacher Straße 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 9180-0 Fax: <49> (89) 9 29 30 00 Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000 Fax: <44> (1628) 778322 Hitachi Asia Pte. Ltd. 16 Collyer Quay #20-00 Hitachi Tower Singapore 049318 Tel: 535-2100 Fax: 535-1533

Hitachi Asia Ltd. Taipei Branch Office 3F, Hung Kuo Building. No.167, Tun-Hwa North Road, Taipei (105) Tel: <886> (2) 2718-3666 Fax: <886> (2) 2718-8180 Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Tsim Sha Tsui, Kowloon, Hong Kong Tel: <852> (2) 735 9218 Fax: <852> (2) 730 0281 Telex: 40815 HITEC HX

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